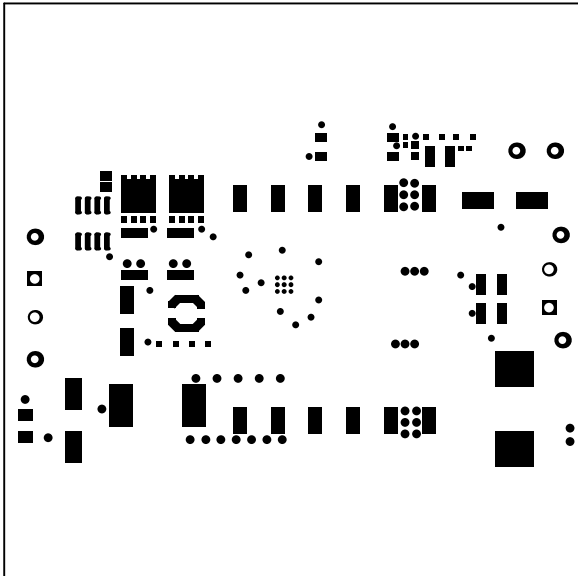
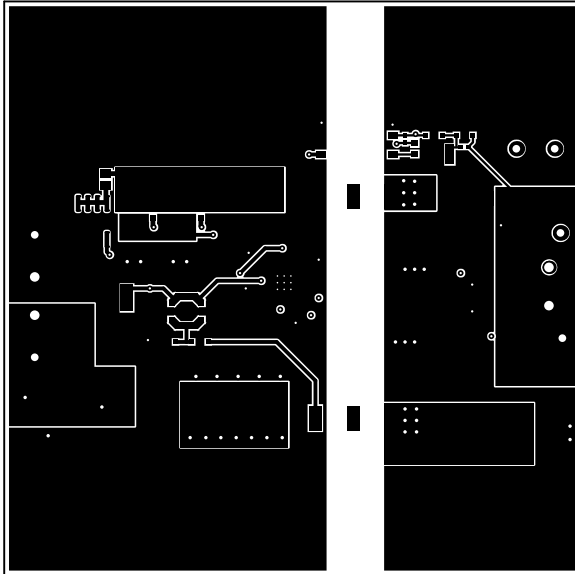




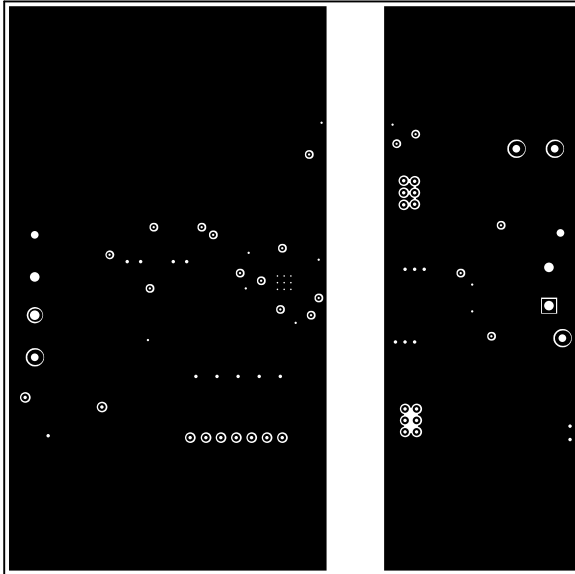
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8866	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 5/15/2013 2:42:53 PM		TEXAS INSTRUMENTS



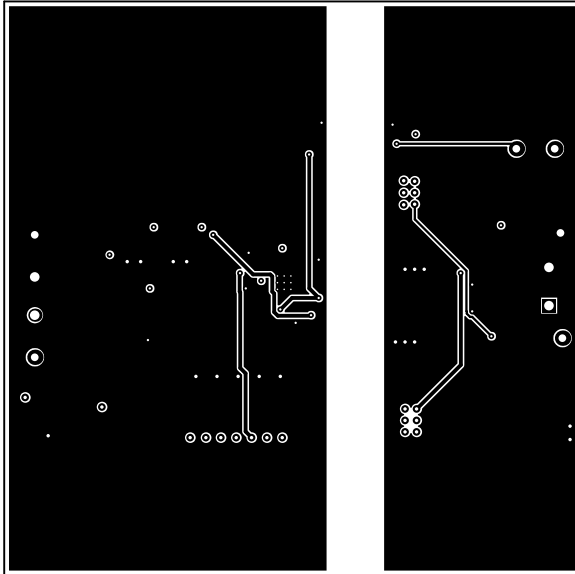
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LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 5/15/2013 2:42:53 PM	TEXAS INSTRUMENTS	



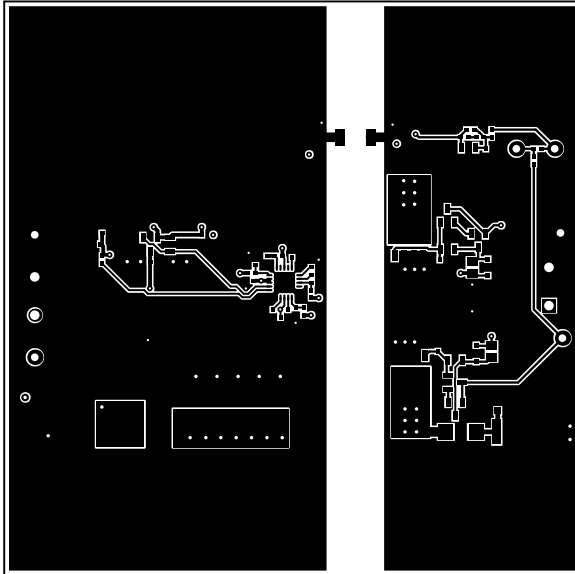
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LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 5/15/2013 2:42:53 PM	TEXAS INSTRUMENTS	



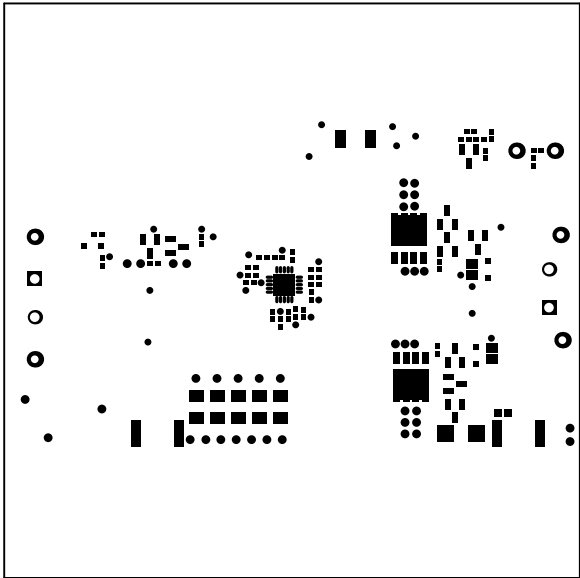
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8866	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline			
PLOT NAME = Mid Layer1	GENERATED : 5/15/2013 2:42:54 PM	TEXAS INSTRUMENTS	



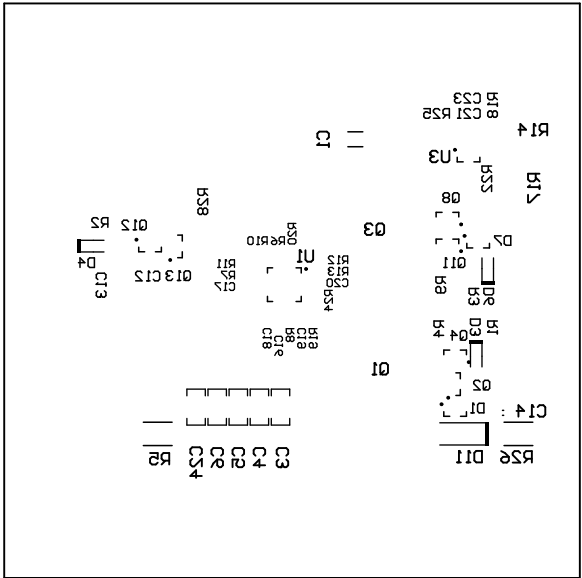
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8866	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline			
PLOT NAME = Mid Layer2	GENERATED : 5/15/2013 2:42:54 PM	TEXAS INSTRUMENTS	



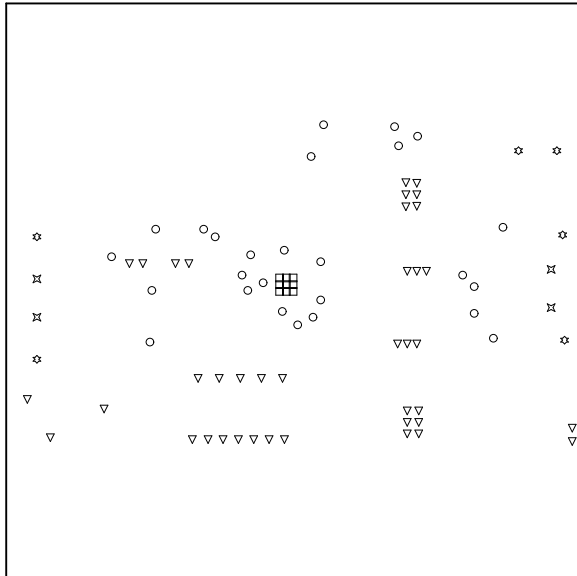
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8866	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 5/15/2013 2:42:55 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8866	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 5/15/2013 2:42:55 PM	TEXAS INSTRUMENTS	



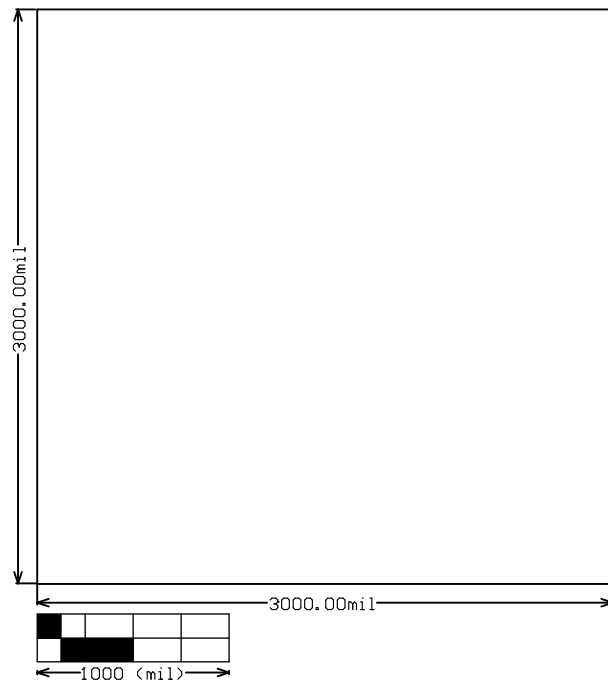
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8866	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 5/15/2013 2:42:56 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
□	9	7.874mil (0.2mm)	PTH	Round
○	26	12mil (0.305mm)	PTH	Round
▽	39	18mil (0.457mm)	PTH	Round
☆	6	40mil (1.016mm)	PTH	Round
✕	4	49.213mil (1.25mm)	PTH	Round
84 Total				

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8866	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 5/15/2013 2:42:56 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8866	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 5/15/2013 2:42:57 PM	TEXAS INSTRUMENTS	

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